

## Materials Declaration

<b>Package</b>	TQFP_EP
<b>Body Size</b>	7 x 7 x 1.0 (3.5 mm exposed pad)
<b>LeadCount</b>	48
<b>Option</b>	Pb-free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
SiO2 Filler	88.00	6.98 E-02	513753
Multi-aromatic Resin	11.50	9.12 E-03	67137
Carbon black	0.50	3.97 E-04	2922
Subtotal		7.93 E-02	583812

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	99.25	4.10 E-02	301810
Cr	0.30	1.24 E-04	913
Sn	0.25	1.03 E-04	758
Zn	0.20	8.30 E-05	611
Subtotal		4.13 E-02	304092

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100.0	5.60 E-04	4122

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100.0	3.64 E-03	26800

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	1.26 E-03	9238

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100.0	7.34 E-03	54042

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	1.70 E-03	12528
Resin	20.0	4.86 E-04	3577
Anhydride	10.0	2.43 E-04	1789
Subtotal		2.43 E-03	17894

Molding Compound		
Item	PPM	Method
Pb	None Detected	USEPA 3052. ICP-AES.
Cd	None Detected	USEPA 3052. ICP-AES.
Hg	None Detected	USEPA 3052. ICP-AES.
Cr+6	None Detected	USEPA 3060A & 7196A.
PBB	None Detected	USEPA 8081A/8270D/3540C/3550C.GC/MS.
PBDE	None Detected	USEPA 8081A/8270D/3540C/3550C.GC/MS.

Die Attach Paste		
Item	PPM	Method
Pb	None Detected	EPA Method 3051A/3052. ICP-OES
Cd	None Detected	EPA Method 3051A/3052. ICP-OES
Hg	None Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	None Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	None Detected	EPA Method /3550C. GC/MS.
PBDE	None Detected	EPA Method /3550C. GC/MS.

Package Totals		
Weight (g)	PPM	
1.36 E-01	1000000	

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

## Materials Declaration

<b>Package</b>	TQFP_EP
<b>Body Size</b>	7 x 7 x 1.0 (3.5 mm exposed pad)
<b>LeadCount</b>	48
<b>Option</b>	SnPb

### Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	88.00	6.98 E-02	512621
Multi-aromatic Resin	11.50	9.12 E-03	66989
Carbon black	0.50	3.97 E-04	2916
Subtotal		7.93 E-02	582526

### Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.25	4.10 E-02	301145
Cr	0.30	1.24 E-04	911
Sn	0.25	1.03 E-04	756
Zn	0.20	8.30 E-05	610
Subtotal		4.13 E-02	303422

### Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100.0	5.60 E-04	4113

### External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85.0	3.35 E-03	24604
Pb	15.0	5.91 E-04	4341
Subtotal		3.94 E-03	28945

### Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.26 E-03	9217

### Chip

Item	% of Chip	Weight (g)	PPM
Si	100.0	7.34 E-03	53923

### Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	1.70 E-03	12500
Resin	20.0	4.86 E-04	3569
Anhydride	10.0	2.43 E-04	1785
Subtotal		2.43 E-03	17854

### Package Totals

Weight (g)	PPM
1.36 E-01	1000000

### Molding Compound

Item	PPM	Method
Pb	None Detected	USEPA 3052. ICP-AES.
Cd	None Detected	USEPA 3052. ICP-AES.
Hg	None Detected	USEPA 3052. ICP-AES.
Cr+6	None Detected	USEPA 3060A & 7196A.
PBB	None Detected	USEPA 8081A/8270D/3540C/3550C. GC/MS.
PBDE	None Detected	USEPA 8081A/8270D/3540C/3550C. GC/MS.

### Die Attach Paste

Item	PPM	Method
Pb	None Detected	EPA Method 3051A/3052. ICP-OES
Cd	None Detected	EPA Method 3051A/3052. ICP-OES
Hg	None Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	None Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	None Detected	EPA Method /3550C. GC/MS.
PBDE	None Detected	EPA Method /3550C. GC/MS.

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary